Serial Number: 09/785,006

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Title: GRINDING TECHNIQUE FOR INTEGRATED CIRCUITS Dkt: 303.259US3

IN THE SPECIFICATION

Please amend the specification as follows.

The paragraph beginning at page 1, after the title is amended as follows:

This application is a Continuation of U.S. Application No. 09/137,521, filed August 20, 1998, now U.S. Patent No. 6,215,172, which is a Divisional of U.S. Application No. 08/795,693, filed February 4, 1997, now U.S. Patent No. 6,127,245. These applications are incorporated herein by reference.